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Overview of interconnect technologies

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Interconnection technologies are important for compact modern tracking detectors. Recently new developments come to the focus which allow a wide variety of new detector layouts and arrangements. Among these are fine pitch bump bonding with pitches down to 50μm and below and Through Silicon Via (TSV) conncetion through the electronics layer of hybrid pixel detector. Real 3D integration of several electronics layer is another attractive approach to compact the detector design. In this presentation on overview of these interconnection is given as they are currently tested for future particle physics tracking detectors.

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